TOSHIBA

MICROWAVE SEMICONDUCTOR TECHNICAL DATA

MICROWAVE POWER GaAs FET TIM5964-16EL

FEATURES

- HIGH POWER
 P1dB=42.5dBm at 5.9GHz to 6.4GHz
- HIGH GAIN
 G1dB= 11.5dB at 5.9GHz to 6.4GHz
- BROAD BAND INTERNALLY MATCHED FET
- HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain	P1dB		dBm	41.5	42.5	_
Compression Point						
Power Gain at 1dB Gain	G1dB	VDS= 10V	dB	10.5	11.5	
Compression Point		IDSset=2.8A				
Drain Current	IDS1	f = 5.9 to 6.4GHz	Α		4.4	5.0
Gain Flatness	ΔG		dB			±0.8
Power Added Efficiency	ηadd		%	_	38	_
3rd Order Intermodulation	IM3	Two-Tone Test	dBc	-40	-45	_
Distortion		Po= 30.5dBm				
Drain Current	IDS2	(Single Carrier Level)	Α			5.0
Channel Temperature Rise	ΔTch	(VDS X IDS + Pin – P1dB) X Rth(c-c)	°C			80

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V	S	_	5.2	
		IDS= 5.2A				
Pinch-off Voltage	VGSoff	VDS= 3V	V	-1.0	-1.9	-4.0
		IDS= 40mA				
Saturated Drain Current	IDSS	VDS= 3V	Α		8.8	
		VGS= 0V				
Gate-Source Breakdown	VGSO	IGS= -180μA	V	-5		
Voltage		·				
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W		1.5	1.8

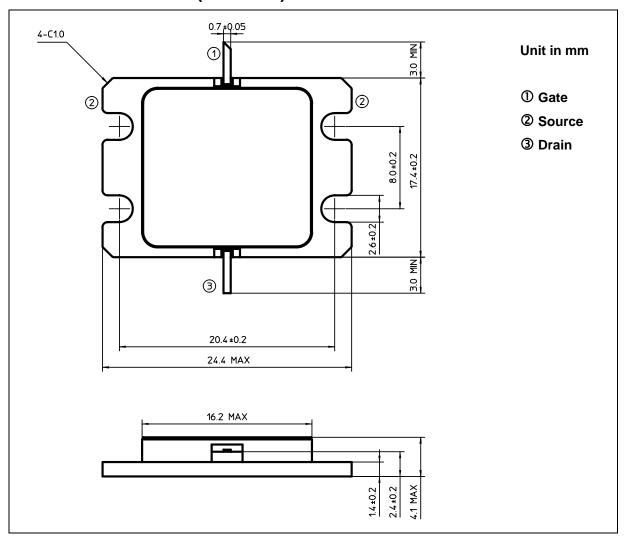
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ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	А	14.0
Total Power Dissipation (Tc= 25 °C)	PT	W	83.3
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 to +175

PACKAGE OUTLINE (7-AA05A)



HANDLING PRECAUTIONS FOR PACKAGE MODEL

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.